TYPE	GEOMETRY	PHYSICAL CHARACTERISTICS	ELECTRICAL CHARACTERISTICS	STANDARD TYPES		
1015 NPN		1. Chip size............ 15 X 19 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad...... B = 4 mils, E = 5 mils	I_C 100 mA max V_{CEO} 30 - 45 Vdc V_{EBO} 15 - 18 Vdc h_{FE} 50 @ 1 mA ft 20 MHz	2N2432 2N2432A 2N4138		
2020 PNP		1. Chip size............ 23 X 16 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 3 X 5 mils, E = 5 X 4 mils	I_C 100 mA max V_{CEO} 35 Vdc V_{EBO} 40 Vdc h_{FE} 100 - 250 @ 1mA ft 15 MHz	2N328 2N329 2N2944A 2N2945A 2N2946A 2N3218 2N3219 2N3677 2N3910 2N3911	2N3912 2N3913 2N4006 2N4007 2N4008 2N4009 2N4010 2N4011 2N6566	
1020B NPN		1. Chip size............ 20 X 20 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad...... B = 5 X 5 mils, E = 6 X 4 mils	I_C 800 mA V_{CEO} 40 Vdc V_{EBO} 6.0 Vdc h_{FE} 100 - 300 @ 150mA ft 300 MHz	2N693 2N696 2N718 2N718A 2N956 2N1420 2N1566 2N2218 2N2218A 2N2219	2N2219A 2N2221 2N2221A 2N2222 2N2222A 2N3299 2N3300 2N3301 2N3302 2N5581	2N5582
2020B PNP		1. Chip size............ 20 X 20 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad...... B = 5 X 5 mils, E = 6 X 4 mils	I_C 600 mA V_{CEO} 60 Vdc V_{EBO} 5.0 Vdc h_{FE} 100 - 300 @ 150mA ft 200 MHz	2N1132 2N2904-A 2N2905-A 2N2906-A 2N2907-A 2N3485-A 2N3486-A 2N3494 2N3638-A 2N3644	2N3645 2N3702 2N3703 2N4036 2N4037 2N4142 2N4143 2N4290 2N4291 2N4402	2N4403 2N4971 2N4972 2N5142 2N5143 2N5221 2N5365

TYPE	GEOMETRY	PHYSICAL CHARACTERISTICS	ELECTRICAL CHARACTERISTICS	STANDARD TYPES		
1040 NPN	E B	1. Chip size............ 40 X 40 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 5 X 8 mils, E = 10 X 7 mils	I_C 1.0 A max V_{CEO} 300 - 350 Vdc V_{EBO} 7.0 Vdc h_{FE} 40 - 160 @ 20 mA f_t 15 MHz	2N3439 2N3440 2N6591 2N6592 2N6593 2N6720 2N6721 2N6722 2N6723 D40P1	D40P3 D40P5	
2040 PNP	E B	1. Chip size............ 40 X 40 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 5 X 8 mils, E = 10 X 7 mils	I_C 1.0 mA max V_{CEO} 200 - 300 Vdc V_{EBO} 6.0 Vdc h_{FE} 30 - 150 @ 50 mA f_t 15 MHz	2N5415 2N5416		
1040B NPN	E B	1. Chip size............ 40 X 40 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 6 X 8 mils, E = 6 X 4 mils	I_C 300 - 500 mA max V_{CEO} 150 Vdc V_{EBO} 6.0 Vdc h_{FE} 100 - 300 @ 150 mA f_t 150 MHz	2N3498 2N3499 2N3500 2N3501		
2040B PNP	E B	1. Chip size............ 40 X 40 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 6 X 8 mils, E = 6 X 4 mils	I_C 1.5 A max V_{CEO} 60 Vdc V_{EBO} 5.0 Vdc h_{FE} 30 - 120 @ 1.0 mA f_t 180 MHz	2N3467 2N3468 2N3762 2N3763 2N3764 2N3765		

TYPE	GEOMETRY	PHYSICAL CHARACTERISTICS	ELECTRICAL CHARACTERISTICS	STANDARD TYPES		
1060 NPN	E B	1. Chip size............ 60 X 60 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 15 X 6 mils, E = 28 X 6 mils	I_C 1 A max V_{CER} 500 - 1000 Vdc V_{EBO} 5.0 V h_{FE} 10 - 100 ft 4 - 100 MHz	2N5095 2N5097 2N5098 2N5099		
2060 PNP	E B	1. Chip size............ 60 X 60 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 15 X 6 mils, E = 28 X 6 mils	I_C 1 A max V_{CEO} 50 - 450 Vdc V_{EBO} 5.0 V h_{FE} 10 - 100 ft 4 - 100 MHz	2N5093 2N5094 2N5096 2N5100		
1075 NPN	E B	1. Chip size............ 75 X 75 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 19 X 8 mils, E = 35 X 8 mils	I_C 7.0 A max V_{CEO} 40 - 400 Vdc V_{EBO} 6.0 Vdc h_{FE} 25 - 100 ft 1.5 - 50 MHz	2N3418 2N3419 2N3420 2N3421 2N3583 2N3584 2N3585 2N3738 2N3739 2N3766	2N3767 2N3879 2N5660 2N5661 2N5662 2N5663	
2075 PNP	E B	1. Chip size............ 75 X 75 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 19 X 8 mils, E = 35 X 8 mils	I_C 5.0 A max V_{CEO} 40 - 300 Vdc V_{EBO} 6.0 Vdc h_{FE} 25 - 100 ft 3.0 - 60 MHz	2N3740 2N3741 2N3867 2N3868 2N4898 2N4899 2N4900 2N5149		

TYPE	GEOMETRY	PHYSICAL CHARACTERISTICS	ELECTRICAL CHARACTERISTICS	STANDARD TYPES		
1085 NPN	E B	1. Chip size............ 85 X 85 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 21 X 8 mils, E = 40 X 8 mils	I_C 1.5 Adc max V_{CEO} 55 - 100 Vdc V_{EBO} 12.0 Vdc h_{FE} 35 - 100 ft 1.5 MHz	2N1479 2N1480 2N1481 2N1482 2N1483 2N1484 2N1485 2N1486 2N1701		
2085 PNP	E B	1. Chip size............ 85 X 85 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 21 X 8 mils, E = 40 X 8 mils	I_C 4.0 Adc max V_{CEO} 80 Vdc V_{EBO} 7.0 Vdc h_{FE} 30 - 100 @ 250mA ft 4.0 MHz	2N3740 2N3741 2N3741A		
1087 NPN	E B	1. Chip size............ 87 X 100 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B_1 = 16 X 14 mils, B_2 = 16 X 18 mils, E = 40 X 8 mils	I_C 5 Adc max V_{CEO} 80 - 150 Vdc V_{EBO} 12.0 Vdc h_{FE} 1000 - 10,000 ft 50 MHz	2N6350 2N6351 2N6352 2N6353		
1120 NPN	E B	1. Chip size............ 120 X 120 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 52 X 12 mils, E = 84 X 12 mils	I_C 10 Adc max V_{CEO} 60 - 400 Vdc V_{EBO} 6.0 Vdc h_{FE} 40 - 120 ft 20 MHz	2N4150 2N5002 2N5004 2N5237 2N5238 2N5427 2N5428 2N5429 2N5430 2N5664	2N5665 2N5666	

TYPE	GEOMETRY	PHYSICAL CHARACTERISTICS	ELECTRICAL CHARACTERISTICS	STANDARD TYPES		
2120 PNP	E B	1. Chip size............ 120 X 120 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 52 X 12 mils, E = 84 X 12 mils	I_C 5 Adc max V_{CEO} 80 Vdc V_{EBO} 6.0 Vdc h_{FE} 30 - 240 ft 30 MHz	2N5003 2N5005 2N6190 2N6191 2N6193		
1130 NPN	E B	1. Chip size............ 130 X 130 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 52 X 12 mils, E = 84 X 12 mils	I_C 2.0 Adc max V_{CEO} 200 - 350 Vdc V_{EBO} 6.0 Vdc h_{FE} 10 - 100 ft 20 MHz	2N6211 2N6212 2N6213		
1136 NPN	B E	1. Chip size............ 136 X 136 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 35 X 20 mils, E = 35 X 35 mils	I_C 8.0 Adc max V_{CEO} 80 Vdc V_{EBO} 5.0 Vdc h_{FE} 750 - 18,000 ft 25 MHz	2N6294 2N6295 2N6300 2N6301		
2136 PNP	B E	1. Chip size............ 136 X 136 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 35 X 20 mils, E = 35 X 35 mils	I_C 8.0 Adc max V_{CEO} 80 Vdc V_{EBO} 5.0 Vdc h_{FE} 750 - 18,000 ft 25 MHz	2N6296 2N6297 2N6298 2N6299		

TYPE	GEOMETRY	PHYSICAL CHARACTERISTICS	ELECTRICAL CHARACTERISTICS	STANDARD TYPES		
1170 NPN		1. Chip size............ 170 X 170 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 40 X 30 mils, E = 100 X 20 mils	I_C 20 Adc max V_{CEO} 80 Vdc V_{EBO} 7.0 Vdc h_{FE} 20 - 150 ft 2.5 - 40 MHz	2N1724 2N1724A 2N1725 2N3713 2N3714 2N3715 2N3716 2N5038 2N5039		
2170 PNP		1. Chip size............ 170 X 170 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 40 X 30 mils, E = 100 X 20 mils	I_C 10 Adc max V_{CEO} 80 Vdc V_{EBO} 7.0 Vdc h_{FE} 50 - 180 ft 4.0 MHz	2N3789 2N3790 2N3791 2N3792		
1200 NPN		1. Chip size............ 200 X 200 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 45 X 29 mils, E = 41 X 70 mils	I_C 20 Adc max V_{CEO} 60 - 100 Vdc V_{EBO} 5.0 Vdc h_{FE} 750 - 18,000 ft 4.0 MHz	2N6282 2N6283 2N6284 2N6057 2N6058 2N6059		
2200 PNP		1. Chip size............ 200 X 200 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 45 X 29 mils, E = 41 X 70 mils	I_C 12 Adc max V_{CEO} 80 - 100 Vdc V_{EBO} 5.0 Vdc h_{FE} 750 - 18,000 ft 4.0 MHz	2N6050 2N6051 2N6052		

TYPE	GEOMETRY	PHYSICAL CHARACTERISTICS	ELECTRICAL CHARACTERISTICS	STANDARD TYPES		
1206 NPN		1. Chip size............ 206 X 206 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 24 X 46 mils, E = 18 X 85 mils	I_C 20 Adc max V_{CEO} 75 - 150 Vdc V_{EBO} 7.0 Vdc h_{FE} 20 - 100 ft 60 MHz	2N5038 2N5039 2N6354 2N6496		
1230 NPN		1. Chip size............ 230 X 230 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 30 X 38 mils, E = 33 X 156 mils	I_C 25 - 50 Adc max V_{CEO} 80 - 150 Vdc V_{EBO} 6.0 Vdc h_{FE} 15 - 120 ft 2 - 40 MHz	2N5671 2N5672 2N5685 2N5686 2N5885 2N5886 2N6274 2N6277 2N6338 2N6339	2N6340 2N6341	
2230 PNP		1. Chip size............ 230 X 230 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 30 X 38 mils, E = 33 X 156 mils	I_C 25 Adc max V_{CEO} 80 - 120 Vdc V_{EBO} 6.0 Vdc h_{FE} 20 - 120 ft 40 MHz	2N5883 2N5884 2N6436 2N6437 2N6438		
1250 NPN		1. Chip size............ 250 X 250 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 25 X 30 mils, E = 35 X 60 mils	I_C 20 Adc max V_{CEO} 400 - 550 Vdc V_{EBO} 2.0 Vdc h_{FE} 25 - 100 ft 100 MHz	SVT6060 SVT6061 SVT6062		

TYPE	GEOMETRY	PHYSICAL CHARACTERISTICS	ELECTRICAL CHARACTERISTICS	STANDARD TYPES		
2252 PNP		1. Chip size............ 250 X 250 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 25 X 30 mils, E = 35 X 60 mils	I_C 20 Adc max V_{CEO} 60 - 100 Vdc V_{EBO} 5.0 Vdc h_{FE} 750 - 18,000 ft 4.0 MHz	2N6285 2N6286 2N6287		
2260 PNP		1. Chip size............ 260 X 260 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 53 X 100 mils, E = 42 X 22 mils	I_C 50 Adc max V_{CEO} 60 - 80 Vdc V_{EBO} 5.0 Vdc h_{FE} 15 - 60 ft 2.0 MHz	2N5683 2N5684		
1270B NPN		1. Chip size............ 270 X 270 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 25 X 70 mils, E = 40 X 80 mils	I_C 15 Adc max V_{CEO} 300 - 450 Vdc V_{EBO} 8.0 Vdc h_{FE} 8 @ 15 A / 3 V ft 15 MHz	2N6674 2N6675 2N6676 2N6677 2N6678 2N6691 2N6692 2N6693		
1330 NPN		1. Chip size............ 330 X 330 mils ± 2 mils 2. Chip thickness.... 8 - 12 mils nominal 3. Top metal........... Aluminum 25,000Å minimum, 30,000Å nominal 4. Back metal.......... A. Ti/Ni/Ag 2kÅ/7kÅ/7kÅ min. 3kÅ/10kÅ/10kÅ nom. B. Gold 1,500Å minimum, 2,500Å nominal 5. Backside............ Collector 6. Bonding pad....... B = 35 X 67 mils, E = 52 X 120 mils	I_C 30 Adc max V_{CEO} 250 - 400 Vdc V_{EBO} 5.0 Vdc h_{FE} 30 - 150 ft 10 MHz	2N6322 2N6323		